



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-07-13
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giapello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC572L64F2ENGAC	A9R6*FE64ACQ	A	1054	2017-07-13
Amount	UoM	Unit type	ST ECOPACK Grade	
260.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiPd	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10-10-1	80	gull wing	
Comment	TQFP-EP 80L 10X10X1.0 EXPADDDOWN			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.04	Die - Leadframe	3981

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	A9R6*FE64ACQ									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	36.060	mg	supplier	die	Silicon (Si)	7440-21-3		35.505	mg	984609	136558				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.039	mg	1082	150				
				supplier	metallization	Copper (Cu)	7440-50-8		0.233	mg	6461	896				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.038	mg	1054	146				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.010	mg	277	38				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	55	8				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.053	mg	1470	204				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.180	mg	4992	692				
				Leadframe	Copper & its alloys	117.039	mg	supplier	alloy	Copper (Cu)	7440-50-8		112.982	mg	965336	434546
								supplier	alloy	Iron (Fe)	7439-89-6		2.657	mg	22702	10219
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.160	mg	1367	615				
supplier	alloy	Zinc (Zn)	7440-66-6						0.139	mg	1188	535				
supplier	metallization	Nickel (Ni)	7440-02-0						1.035	mg	8843	3981				
supplier	metallization	Palladium (Pd)	7440-05-3						0.066	mg	564	254				
Die attach	Other Organic Materials	4.827	mg	supplier	glue	Silver (Ag)	7440-22-4		4.320	mg	894966	16615				
				supplier	glue	isobornyl Methacrylate	7534-94-3		0.362	mg	74995	1392				
				supplier	glue	Bismaleimide resin	Proprietary		0.145	mg	30039	558				
Bonding wires	Other inorganic materials	1.143	mg	supplier	wire	Copper (Cu)	7440-50-8		1.143	mg	1000000	4396				
Encapsulation	Other Organic Materials	100.931	mg	supplier	mold compound	Silica, vitreous	60676-86-0		87.203	mg	863986	335396				
				supplier	mold compound	Epoxy Resin	25068-38-6		7.570	mg	75003	29115				
				supplier	mold compound	Phenol Resin	29690-82-2		5.047	mg	50004	19412				
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.505	mg	5003	1942				
				supplier	mold compound	Quartz	14808-60-7		0.303	mg	3002	1165				
				supplier	mold compound	Carbon black	1333-86-4		0.303	mg	3002	1165				